

In the Claims:

Claim 1 (currently amended): A semiconductor die package comprising:

a housing defining a cavity for holding at least one semiconductor die, said housing including a plurality of insulative side walls, each of said side walls having a bottom surface and an interior wall including a top surface, and an end plate joined to said side walls; and

a plurality of substantially straight conductive leads extending through at least one of said side walls, each of said conductive leads including an internal lead section extending into the cavity from the top surface of the interior wall and an [a] external lead section extending externally from said ~~at least one~~ bottom surface of said side wall.

Claim 2 (original): The semiconductor die package according to claim 1, wherein said side walls and end plate are a one-piece unit.

Claim 3 (currently amended): The semiconductor die package according to claim 1, wherein said insulative side walls are comprised of a liquid crystal polymer.

Claim 4 (original): The semiconductor die package according to claim 1, wherein said side walls include a recess for receiving a cover plate.

Claim 5 (original): The semiconductor die package according to claim 1.

Claim 6 (currently amended): The semiconductor die package according to claim 1, wherein said end plate comprises of a conductive material.

Claim 7 (original): The semiconductor die package according to claim 1, further comprising a cover plate that covers at least a portion of the cavity.

Claim 8 (original): The semiconductor die package according to claim 7, wherein said side walls include a trench for receiving said cover plate.

Claim 9 (original): The semiconductor die package according to claim 8, further comprising an adhesive applied to said trench for securing said cover plate to said housing.

Claim 10 (original): The semiconductor die package according to claim 7, further comprising an adhesive applied to said side walls for securing said cover plate to said housing.

Claim 11 (original): The semiconductor die package according to claim 1, wherein said external lead sections extend at least two different lengths from said at least one bottom surface of said side wall.

Claim 30 (new): The semiconductor die package according to claim 1, wherein said conductive leads include external lead sections that only extend externally from the bottom surface of one or more said side walls.

Claim 31 (new): A semiconductor die package comprising:

a housing defining a cavity for holding at least one semiconductor die, said housing including a plurality of insulative side walls, each of said side walls having a bottom surface, wherein an interior surface of at least one side wall includes two or more ledges, each ledge having a top surface;

an end plate joined to said side walls; and

a plurality of substantially straight conductive leads extending through at least said two or more ledges, each of said conductive leads including an internal lead section extending into the cavity from the top surface of one of said ledges and an external lead section extending externally from said at least one bottom surface of said side wall.